

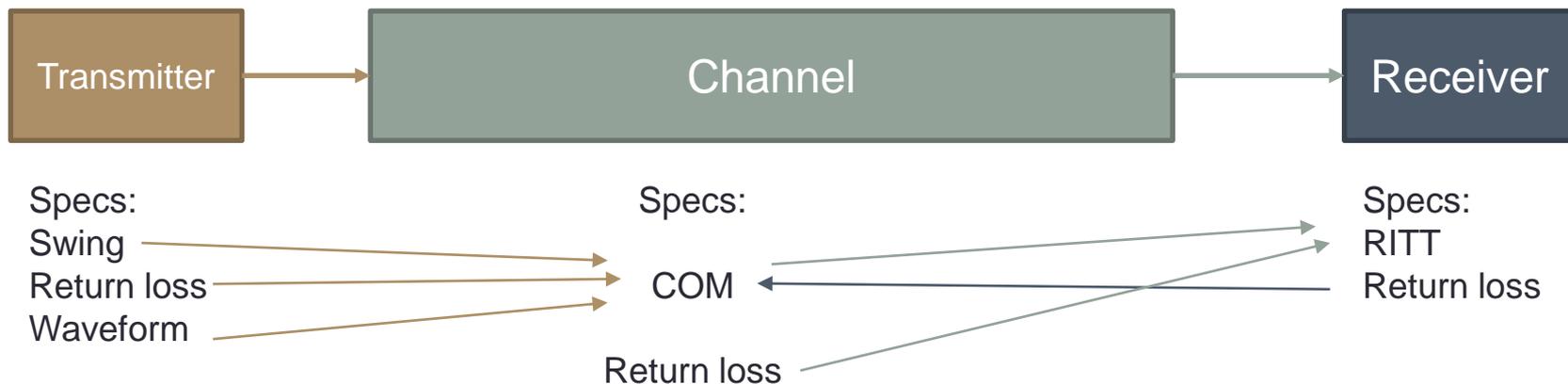
Another look at COM termination parameters and Tx/Rx return loss specifications

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Scope

- This presentation results from several comments and presentations around COM and return loss.
- I'm trying to think out of the box → possibly big changes
- We are converging in WG ballot, so may not want big changes at this point
- There is no new data in this presentation – only ideas
- This may just be an opening of a discussion, without changing anything now
 - Although there is comment #18 in case we agree on something...
 - I would welcome follow-up by other people

background



Maximum power transfer theorem (Jacobi's law)

“to obtain maximum external power from a source with a finite internal resistance, the resistance of the load must equal the resistance of the source” (source: [Wikipedia](#))

But there are other criteria...

Reflection-free matching: $Z_{load} = Z_{source}$

Maximum power transfer matching with reactive circuits: $Z_{load} = Z_{source}^*$

Maximum voltage drop on the load: $|Z_{load}| \gg |Z_{source}|$

Channel perspective

- Our reference differential impedance is 100 Ω
 - (“shall” in 136.11.1, also COM parameter R_0 is 50 Ω , and all precedence)
- We specify the channel using COM which assumes specific terminations of the transmitter and the receiver.
- Is 100 Ω always the best impedance?
 - A channel which is very close to 100 Ω may cause reflections and degrade system BER with Tx/Rx that are not 100 Ω (this can sometimes be seen in COM).
 - A channel that matches the actual impedance of the non-100 Ω Tx and Rx may have bad return loss, but improved system BER (this can be seen in COM too).
- **Practical systems sometimes use other impedances**
 - Intel “recommends” 85 $\Omega \pm 15\%$ for PCIe/HDMI/DVI/DP; USB type C is specified as 85 $\Omega \pm 10\%$
 - Lower impedance reduces insertion loss and may improve matching with some connectors...

Transmitter perspective

- Reference differential impedance is 100 Ω (120D.3.1.1, and all precedence)
- A transmitter that deviates from 100 Ω may show bad return loss.
 - It may also have degraded pulse shape results when measured with a 50 Ω scope termination.
- A transmitter which is very close to 100 Ω may cause reflections with a channel that is not 100 Ω , which may degrading system BER.
- A transmitter that matches the actual impedance of the channel may have bad return loss, but actually lower reflections, and improve system BER.
- **Transmitter termination may be configurable!**
 - This may also affect voltage swing on a given load (depending on transmitter design)
 - There may be a tradeoff between signal amplitude, crosstalk, and reflections
 - There are practical cases where one setting is used for meeting RL specs, and another setting is used for optimizing BER on a given channel
 - We ignore that in all our standards – both Tx specs and channel specs.

Receiver perspective

- Return loss specs for Rx are a matter of continuous debate
 - BER is the objective; it is measured in RITT; why should we care about RL?
 - ... because the channels are specified with some assumptions on the Rx.
 - If a system (combination of Tx+channel+Rx) works as expected, we shouldn't care about RL; but if a system fails, the Rx RL might be the culprit.
- Rx matched to the channel would reduce reflections
 - But the Rx typically includes active circuits – it does not use only the power delivered from the channel
 - This is quite different from optical or RF systems where power really matters
- Impedance matched Rx may or may not be the best thing
 - Higher Rx termination may provide higher input voltage
 - Tradeoffs with reflections are possible here too
 - Rx termination may be configurable too
 - We ignore that too...

...and other assorted problems

- RL is specified as a per-frequency mask; failing the mask at some frequencies may be insignificant
- RL is specified in the frequency domain by magnitude only; but we use baseband signaling and phase *is* significant
- Some reflection effects can be mitigated by equalization, like the kind we assume (CTLE and short DFE)
- So should we care at all?

Can we stop specifying (or relax) RL?

- This author's opinion is: no
 - For compliance, **there should be one reference and limits to how much you can deviate – otherwise, there is no interoperability**
 - The methods may change from what we have today (e.g. we may adopt ERL)
- But we may acknowledge that actual systems may deviate from 100 Ω
 - Copper cable is part of a pluggable/interoperable ecosystem; moving it to another impedance is a longshot
 - But **backplanes and AUI-C2C are engineered interconnects**
- We may explicitly allow a device that is compliant at 100 Ω to be configured to another impedance if it improves BER in a certain system
 - E.g. using MDIO registers
 - Compliance at another impedance setting can be checked using renormalization
 - This may improve design flexibility

Proposals for the near term

- For backplane (and possibly AUI-C2C)
 - Specify COM with nominal $R_d=50\Omega$ (or another single value if there is consensus)
 - This may improve results
 - Quantify the possible COM degradation with combinations of other R_d values that still enable meeting the Tx/Rx RL specs (whichever way they are expressed)
 - My estimate based on prior presentations: 0.5 dB. More analysis may be done with increased coverage.
 - Increase min COM from 3 dB by the degradation we find, to account for allowed mismatches.
 - Add an informative note that engineered systems may be designed with differential impedance different than 100Ω ; in such systems, COM termination parameters should be modified and RL measurements should be renormalized.
- For cable assembly
 - Specify COM with nominal $R_d=50\Omega$ and $Z_c=100\Omega$ for the host PCBs (or another single value for each, if there is consensus)
 - Use similar quantification of degradation (default: 1 dB) and increase minimum COM accordingly
 - No informative note here

Future ideas

- Standardize configurable terminations for performance optimization
 - MDIO registers, set during training, compliance methods

QUESTIONS/COMMENTS?

Thank you